

Mohd Foad

List of Publications by Year in descending order

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Version: 2024-02-01

16
papers

190
citations

1163117

8
h-index

1372567

10
g-index

16
all docs

16
docs citations

16
times ranked

115
citing authors

#	ARTICLE	IF	CITATIONS
1	Fractal Dimensions of a Propagating Fatigue Crack in Metallic Materials. Journal of Failure Analysis and Prevention, 2021, 21, 1644-1651.	0.9	5
2	Predictive maintenance model for centrifugal pumps under improper maintenance conditions. AIP Conference Proceedings, 2020, , .	0.4	1
3	Mass Migration Damaged Based Model and the Behaviour of Electromigration and Thermomigration in Interconnect. , 2018, , .		0
4	Methodology for reliability assessment of steel wire ropes under fretting fatigue conditions. Journal of Mechanical Engineering and Sciences, 2017, 14, 2488-2502.	0.6	14
5	Rate-dependent responses of electroless plated and sputtered copper layer during nanoindentation loading. , 2016, , .		1
6	A review of computational damage mechanics of mass transport in solder joint. , 2014, , .		0
7	Influence of Thermomigration on Lead-Free Solder Joint Mechanical Properties. Journal of Electronic Packaging, Transactions of the ASME, 2009, 131, .	1.8	33
8	Damage Mechanics of Low Temperature Electromigration and Thermomigration. IEEE Transactions on Advanced Packaging, 2009, 32, 478-485.	1.6	17
9	Low temperature electromigration and thermomigration in lead-free solder joints. Mechanics of Materials, 2009, 41, 1223-1241.	3.2	17
10	Thermomigration Versus Electromigration in Microelectronics Solder Joints. IEEE Transactions on Advanced Packaging, 2009, 32, 627-635.	1.6	30
11	Thermomigration induced degradation in solder alloys. Journal of Applied Physics, 2008, 103, .	2.5	38
12	Simulating Damage Mechanics of Electromigration and Thermomigration. Simulation, 2008, 84, 391-401.	1.8	17
13	Low temperature electromigration and thermomigration in lead-free solder joints. , 2008, , .		0
14	Thermomigration in lead-free solder joints. International Journal of Materials and Structural Integrity, 2008, 2, 11.	0.1	16
15	Thermomigration Induced Strain Field Simulation for Microelectronic Lead Free Solder Joints. , 2006, , .		0
16	Experimental Study of Thermomigration in Lead-Free Nanoelectronics Solder Joints. , 2006, , .		1